

FI/F-term Search

MENU | **NEWS** | **HELP**

Data Type

This choice can be omitted. (When you have no check, all Data Types are chosen.)

Patent Examined utility model registration Patent specification Examined utility model specification

Theme --- e.g. 2C001

Enter a F-term Theme in the box below.

5F043

Publication Date --- e.g. 20010101-20031231

You can specify a range of Publication Date to narrow your search.

This choice can be omitted.

From: - To:

FI/F-term/facet --- e.g. AA01+[A63F9/22-ZAA]

Enter the query into the box below, up to 500 letters (essential requirement for searching)

Boolean operators : "+" means 'OR', "*" means 'AND', "-" means 'NOT'.

DD13

**Display Type**

All Pages

**Priority of search result display**

Check the kind of document, which you want to indicate the Search Result (Document Number).

unexamined applications examined applications

Hit list can be displayed when the search results are within 500.

Search Results 89

| | | |
|--------------|---|---|
| NEWS 1 | Web Page URLs for STN Seminar Schedule - N. America | |
| NEWS 2 | "Ask CAS" for self-help around the clock | |
| NEWS 3 | SEP 01 | New pricing for the Save Answers for SciFinder Wizard within STN Express with Discover! |
| NEWS 4 | OCT 28 | KOREPAT now available on STN |
| NEWS 5 | NOV 30 | PHAR reloaded with additional data |
| NEWS 6 | DEC 01 | LISA now available on STN |
| NEWS 7 | DEC 09 | 12 databases to be removed from STN on December 31, 2004 |
| NEWS 8 | DEC 15 | MEDLINE update schedule for December 2004 |
| NEWS 9 | DEC 17 | ELCOM reloaded; updating to resume; current-awareness alerts (SDIs) affected |
| NEWS 10 | DEC 17 | COMPUAB reloaded; updating to resume; current-awareness alerts (SDIs) affected |
| NEWS 11 | DEC 17 | SOLIDSTATE reloaded; updating to resume; current-awareness alerts (SDIs) affected |
| NEWS 12 | DEC 17 | CERAB reloaded; updating to resume; current-awareness alerts (SDIs) affected |
| NEWS 13 | DEC 17 | THREE NEW FIELDS ADDED TO IFIPAT/IFIUDB/IFICDB |
| NEWS EXPRESS | OCTOBER 29 CURRENT WINDOWS VERSION IS V7.01A, CURRENT MACINTOSH VERSION IS V6.0c(ENG) AND V6.0Jc(JP), AND CURRENT DISCOVER FILE IS DATED 11 AUGUST 2004 | |
| NEWS HOURS | STN Operating Hours Plus Help Desk Availability | |
| NEWS INTER | General Internet Information | |
| NEWS LOGIN | Welcome Banner and News Items | |
| NEWS PHONE | Direct Dial and Telecommunication Network Access to STN | |
| NEWS WWW | CAS World Wide Web Site (general information) | |

Enter NEWS followed by the item number or name to see news on that specific topic.

All use of STN is subject to the provisions of the STN Customer agreement. Please note that this agreement limits use to scientific research. Use for software development or design or implementation of commercial gateways or other similar uses is prohibited and may result in loss of user privileges and other penalties.

FILE 'HOME' ENTERED AT 11:42:15 ON 27 DEC 2004

FILE 'INSPEC' ENTERED AT 11:42:26 ON 27 DEC 2004
Compiled and produced by the IEE in association with FIZ KARLSRUHE
COPYRIGHT 2004 (c) INSTITUTION OF ELECTRICAL ENGINEERS (IEE)

FILE LAST UPDATED: 20 DEC 2004 <20041220/UP>
FILE COVERS 1969 TO DATE

<<< SIMULTANEOUS LEFT AND RIGHT TRUNCATION AVAILABLE IN
THE BASIC INDEX >>>

=> s spin etching
214967 SPIN
56925 ETCHING
L1 10 SPIN ETCHING
(SPIN(W) ETCHING)

$\eta > 0.33 \cdot 10^{-16}$

L1 ANSWER 1 OF 10 INSPEC (C) 2004 IEE on STN

Full Text References

AN 2004:8024784 INSPEC DN B2004-08-2240-008
TI The challenge of ultra thin chip assembly.
AU Feil, M.; Adler, C.; Hemmetzberger, D.; Konig, M.; Bock, K.
(Fraunhofer-Inst. for Reliability & Microintegration, Munchen, Germany)
SO 2004 Proceedings. 54th Electronic Components and Technology Conference
(IEEE Cat. No.04CH37546)
Piscataway, NJ, USA: IEEE, 2004. p.35-40 Vol.1 of 2090 pp. 7 refs.
Conference: Las Vegas, NV, USA, 1-4 June 2004
Price: CCCC 0-7803-8365-6/04/\$20.00
ISBN: 0-7803-8365-6
DT Conference Article
TC Practical
CY United States
LA English

L1 ANSWER 2 OF 10 INSPEC (C) 2004 IEE on STN

Full Text References

AN 2004:7955919 INSPEC DN B2004-06-2550E-056
TI Fabrication of thin film transistors on plastic substrates by spin
etching and device transfer process.
AU Shuo-Cheng Wang; Chung-Ti Hsu; Ching-Fa Yeh; Jen-Chung Lou (Dept. of
Electron. Eng. & Inst. of Electron., Nat. Chiao Tung Univ., Hsinchu,
Taiwan)
SO Proceedings of the SPIE - The International Society for Optical
Engineering (2004) vol.5276, no.1, p.376-83. 11 refs.
Published by: SPIE-Int. Soc. Opt. Eng
Price: CCCC 0277-786X/04/\$15.00
CODEN: PSISDG ISSN: 0277-786X
SICI: 0277-786X(2004)5276:1L.376:FTFT;1-4
Conference: Device and Process Technologies for MEMS, Microelectronics,
and Photonics III. Perth, SA, Australia, 10-12 Dec 2003
DT Conference Article; Journal
TC Application; Experimental
CY United States
LA English

L1 ANSWER 3 OF 10 INSPEC (C) 2004 IEE on STN

Full Text References

AN 2003:7654817 INSPEC DN B2003-07-2550E-051
TI Stability investigation of single-wafer process by using a spin etcher.
AU Tsung-Kuei Kang (Dept. of Electron. Eng., Feng-Chia Univ., Taichung,
Taiwan); Chih-Cheng Wang; Bing-Yue Tsui; Wen-Luh Yang; Feng-Tso Chien;
Shui-Yuan Yang; Chin-Yen Chang; Yuan-Hsin Li
SO Electrochemical and Solid-State Letters (July 2003) vol.6, no.7, p.G85-7.
10 refs.
Published by: Electrochem. Soc
Price: CCCC 1099-0062/2003/6(7)/G85/3/\$7.00
CODEN: ESLEF6 ISSN: 1099-0062
SICI: 1099-0062(200307)6:7L.g85:SISW;1-T
DT Journal
TC Application; Experimental
CY United States
LA English

L1 ANSWER 4 OF 10 INSPEC (C) 2004 IEE on STN

Full Text References

AN 2003:7636124 INSPEC DN B2003-06-0170J-037
TI Packaging technologies for flexible systems.
AU Kallmayer, C.; Bock, K.; Aschenbrenner, R.; Reichl, H. (Fraunhofer Inst.
Zuverlassigkeit und Mikrointegration, Berlin, Germany)
SO Proceedings International Conference and Exhibition on Advanced Packaging
and Systems. ICAPS (SPIE Vol.4828)

Washington, DC, USA: IMAPS - Int. Microelectronics & Packaging Soc, 2002.

p.43-5 of 274 pp. 4 refs.

Conference: Reno, NV, USA, 10-13 March 2002

Sponsor(s): IMAPS

ISBN: 0-930815-65-3

DT Conference Article

TC General Review; Practical

CY United States

LA English

L1 ANSWER 5 OF 10 INSPEC (C) 2004 IEE on STN

Full Text **Abstract**

AN 2002:7434575 INSPEC DN B2002-12-2550E-043

TI Preparation of silicon-on-insulator wafer using spin etching and a subsequent selective etching process.

AU Seong-Eun Lee; Seung-Jin Oh; Sang-Mun So; Heon-Do Kim; Sung-Woong Chung; Hyun-Chul Sohn (Memory R&D Div., Hynix Semicond. Co. Ltd., Kyoungki, South Korea)

SO Japanese Journal of Applied Physics, Part 1 (Regular Papers, Short Notes & Review Papers) (Aug. 2002) vol.41, no.8, p.5024-9. 24 refs.

Published by: Japan Soc. Appl. Phys

CODEN: JAPNDE ISSN: 0021-4922

SICI: 0021-4922(200208)41:8L.5024:PSIW;1-S

DT Journal

TC Practical; Experimental

CY Japan

LA English

L1 ANSWER 6 OF 10 INSPEC (C) 2004 IEE on STN

Full Text **Abstract**

AN 2001:7039608 INSPEC DN B2001-10-7230M-028

TI A CMOS integrated three-axis accelerometer fabricated with commercial submicrometer CMOS technology and bulk-micromachining.

AU Takao, H. (Dept. of Electr. & Electron. Eng., Toyohashi Univ. of Technol., Japan); Fukumoto, H.; Ishida, M.

SO IEEE Transactions on Electron Devices (Sept. 2001) vol.48, no.9, p.1961-8. 18 refs.

Doc. No.: S0018-9383(01)06903-9

Published by: IEEE

Price: CCCC 0018-9383/2001/\$10.00

CODEN: IETDAI ISSN: 0018-9383

SICI: 0018-9383(200109)48:9L.1961:CITA;1-0

DT Journal

TC Experimental

CY United States

LA English

L1 ANSWER 7 OF 10 INSPEC (C) 2004 IEE on STN

Full Text **Abstract**

AN 2001:6799432 INSPEC DN B2001-02-2570-002

TI Ultra thin ICs open new dimensions for microelectronic systems.

AU Klink, G.; Landesberger, C.; Feil, M.; Ansorge, F.; Aschenbrenner, R. (Fraunhofer Inst. for Reliability & Microintegration IZM, Munich, Germany)

SO Advancing Microelectronics (July-Aug. 2000) vol.27, no.4, p.23-5. 7 refs.

Published by: IMAPS-Int. Microelectron. & Packaging Soc

CODEN: ADMIFA

DT Journal

TC Application; Practical

CY United States

LA English

L1 ANSWER 8 OF 10 INSPEC (C) 2004 IEE on STN

Full Text **Abstract**

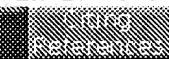
AN 2000:6636119 INSPEC DN B2000-08-7230M-047
TI Fabrication of a three-axis accelerometer integrated with commercial 0.8
mu m-CMOS circuits.
AU Takao, H. (Dept. of Electr. & Electron. Eng., Toyohashi Univ. of Technol.,
Japan); Fukumoto, H.; Ishida, M.
SO Proceedings IEEE Thirteenth Annual International Conference on Micro
Electro Mechanical Systems (Cat. No.00CH36308)
Piscataway, NJ, USA: IEEE, 2000. p.781-6 of xiv+810 pp. 6 refs.
Conference: Miyazaki, Japan, 23-27 Jan 2000
Sponsor(s): IEEE Robotics & Autom. Soc.; Micromachine Center
Price: CCCC 0 7803 5273 4/2000/\$10.00
ISBN: 0-7803-5273-4
DT Conference Article
TC Practical; Experimental
CY United States
LA English

L1 ANSWER 9 OF 10 INSPEC (C) 2004 IEE on STN

 
Full Text

AN 1991:3955183 INSPEC DN B91056059
TI Spin etcher for removal of backside depositions.
AU Gaulhofer, E. (AMS Microsystems, Graz, Austria)
SO Solid State Technology (May 1991) vol.34, no.5, p.57-8, 219. 0 refs.
CODEN: SSTEAP ISSN: 0038-111X
DT Journal
TC Practical
CY United States
LA English

L1 ANSWER 10 OF 10 INSPEC (C) 2004 IEE on STN

 
Full Text

AN 1989:3457364 INSPEC DN A89117018; B89061493
TI Silicon surface passivation by hydrogen termination: a comparative study
of preparation methods.
AU Fenner, D.B. (Xerox Palo Alto Res. Center, CA, USA); Biegelsen, D.K.;
Bringans, R.D.
SO Journal of Applied Physics (1 July 1989) vol.66, no.1, p.419-24. 23 refs.
Price: CCCC 0021-8979/89/130419-06\$02.40
CODEN: JAPIAU ISSN: 0021-8979
DT Journal
TC Experimental
CY United States
LA English

=>